AN3248NK

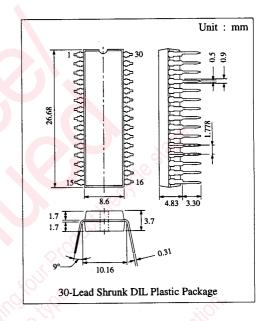
VCR Luminance Signal Processor IC

■ Description

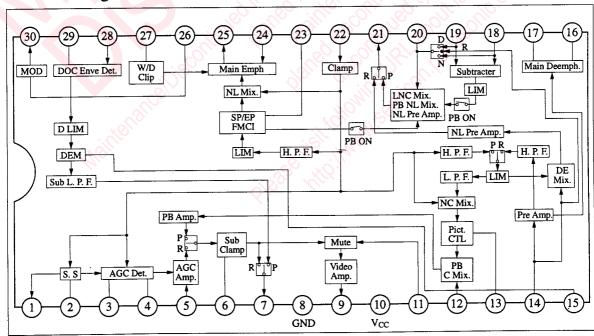
The AN3248NK is an integrated circuit for VCR luminance signal processing. The IC has all the functions integrated on it, which are required for VCR luminance signal processing, and have made great rationalization of external parts and number of pins by incorporating filters.

Features

- Adjustment-free dark clip used
- Incorporates the filters for non-linear emphasis, noise canceller and detail enhancer to greatly rationalize the external parts and reduce the number of pins



■ Block Diagram



AN3248NK

■ Absolute Maximum Ratings (Ta=25°C)

Item	Symbol	Rating	Unit
Supply Voltage	Vcc	6	v
Supply Current	Icc	68	mA
Power Dissipation	P _D	490	mW
Operating Ambient Temperature	Topr	-20 ~ +70	°C
Storage Temperature	Tstg	-55 ~ +125	°C

■ Recommended Operating Range (Ta=25°C)

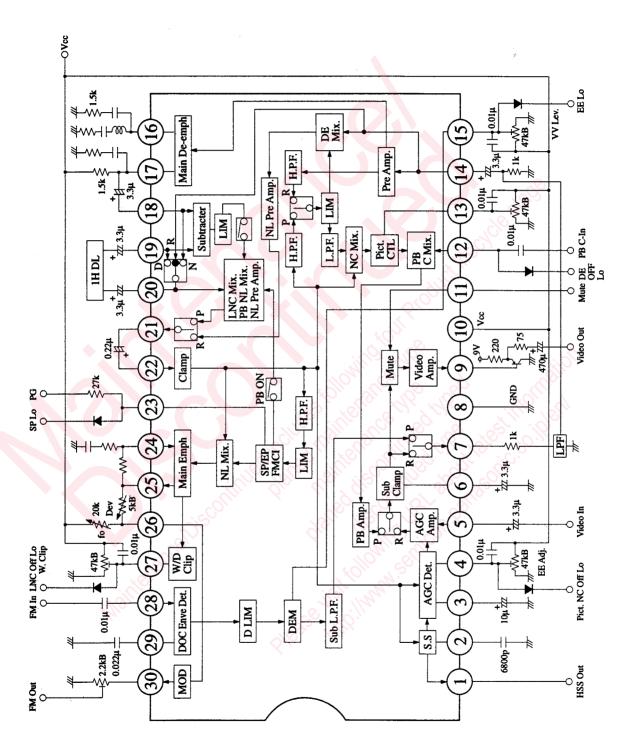
Item	Symbol	Range
Operating Supply Voltage Range	V _{CC}	4.5V ~ 5.5V

■ Electrical Characteristics (Ta=25°C)

Item	Symbol	Condition	min.	typ.	max.	Unit
Circuit current (Rec)	ICCR	Rec mode	30	42	54	mA
Circuit current (PB)	ICCP	PB mode	38	50	62	mA
EE mode holding voltage	VEE	V ₆ =Variable	0	•.4	1.25	v
VV mode holding voltage	V _{VV}	V ₆ =Variable	2.25	, e.S.	5	v
AGC output amplitude	V ₅₋₉	White 100% Vin=1Vpp	1.3	2	2.7	Vpp
D-clip level	ΔV ₅₋₂₅	Solar Way 9120 Filling	40	50	60	%
SS min. input sensitivity	S ₂₂	White 100% Vin=variable	00		450	mVpp
SS pulse output amplitude	V_1	White 100% Vin=1Vpp	4.3			Vpp
FM oscillation output amplitude	V ₃₀	Iin=280μA	0.85	1	1.3	Vpp
FM oscillation second higher harmonic	2f ₃₀	Iin=280μA		-39	-33	dB
FM oscillation control sensitivity	B ₃₀	<u>f(500μA) - f(160μA)</u> 500μA - 160μA	11.5	13	15	kHz /μA
DEM demodulation sensitivity	S ₇	Sine wave, Vs=2.5V Vin=350mVpp, fin=3 ~ 5MHz	40	69	100	mV/MHz
DOC DET ON	S ₂₈	Sine wave, fin=4MHz	-20	-16	-11	dB
DOC DET OFF (hysteresis)	ΔS ₂₈	Sine wave, fin=4MHz	0.2	1.5	6	dB
PB system overall gain	G ₁₄₋₉	White 100% Vin=100mVpp	24	26	30	dB

Application Circuit

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AN3248NK

■ Pin Descriptions

Pin No.	Pin Name	Description	Equivalent Circuit
1	Sync. separate output	Z=50Ω AC=4.7Vop VCC-VCE(sat) -VCE(sat) • Sync. signal separate output	Vvc T
2	Sync. separate detection	DC=2.5V Z=500Ω AC: Sync. Tip detection waveform • Detection pin for the sync. signal separating circuit. Connect the capacitor.	▼V∞
3	AGC detection	DC=2.2V Z=375Ω • Detection pin for the AGC circuit. Connect the capacitor.	У V сс РВ НІ
4	EE level adjustment	OPEN Base Connect the level control VR of the AGC circuit. Low for noise canceller EDIT mode.	⊕ ————————————————————————————————————
5	Video signal input at REC	DC=3V Z=35kΩ AC: Video 1Vpp(std) Video signal input pin (EE). Connect the capacitor	Ø Vcc §
6	Sub Clamp detection	DC=2V (at clamp time) Z=8kΩ (at clamp time) Detection pin for the sub-clamp circuit.	▼ V v v v v v v v v v v v v v v v v v v
7	To Main LPF	DC=1.3V (REC) 1.7V (PB) Z=EF AC=Video 600mVpp (REC) Video 180mVpp (antiphase PB) • AGC output pin at EE. Connect to the main LPF. • DEM output pin at PB. Connect to the main LPF.	Voc T

■ Pin Descriptions (Continue)

Pin No.	Pin Name	Description	Equivalent Circuit
9	EE/VV output	DC=1.1V Z=20Ω AC=Video 2Vpp Video output pin	Ø voc
11	Pseudo V mute control	OPEN Base Mute control pin (CTL for video output) (EE) LowThrough MidMutes to the black level. HiMutes to the white level (PB) LowThrough MidMutes to the pseudo H level. HiMutes to the pseudo V level. Connect the VR.	Vcc Vcc
12	Chroma input at PB	DC=2.7V Z=15kΩ AC=200mVpp (burst) (input should be at low impedance) PB chroma signal input pin Low for detail enhancer OFF mode. Connect the capacitor.	V _{cc}
13	Picture control	DC=2.5V Z=75kΩ At PB Picture control pin (picture quality control) HiHard LoSoft Connect the VR.	⊕ Vcc
14	Pre-amplifier input	DC=3.4V Z=30kΩ AC=Video 300mVpp (REC) Video 90mVpp (antiphase PB) Input a signal from the main low-pass filter. Connect the capacitor.	Vcc Vcc
15	FM demodulation gain control	OPEN Base LoEE mode Mid to HiPlaced in the PB mode and doubles as the PB level control pin. Connect the VR.	Vcc 13

■ Pin Descriptions (Continue)

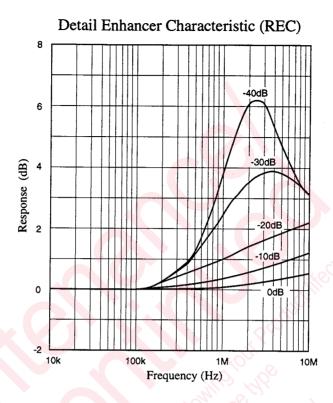
V lee 300mVpp (antiphase) -emphasis circuit (emitter). to GND with 1.5kΩ. nnectable.	-\\\
V (PB) V (EE)	
eo 300mVpp -emphasis circuit (collector). to Vcc with 1.5KΩ. nnectable.	Vcc Ø
eo 300mVpp input a signal from the main de-emphasis collector through capacitor connection. input a 1H delay signal from CCD.	Vcc Vcc
acitance of both pins should be equal.	(B) [
V eo 260mVpp an output pin capacitor for CCD input.	20
in for the non-linear pre-amp.	Vec 20
	Ø Voc
)	leo 1Vpp bin for the non-linear pre-amp. the capacitor, and then, to the next pin. V (Sync. Tip) leo 1Vpp binput pin. pacitor used should be as specified.

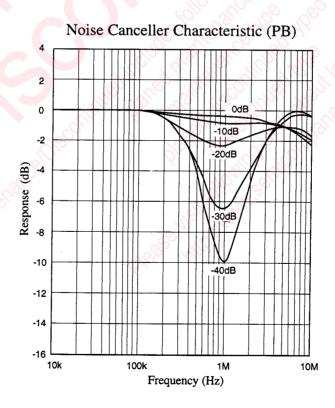
■ Pin Descriptions (Continue)

Pin No.	Pin Name	Description	Equivalent Circuit
23	PG input & 2H/6H change-over	DC=5V (Open) Z=27kΩ LoSP mode. The characteristics of non-linear emphasis and non-linear de-emphasis differ from the EP mode. Mid to HiEP mode. Controls FMCI by switching Mid/Hi.	Ø V cc
24	Feedback amp. input	DC=2V Z=EF (Pin 25) OPEN base (Pin 24) AC=Video 300mV Main emphasis output	Ø Vcc
25	Main emphasis circuit	Pin 24 NF side. Connect LPF. Pin 25 Output side. Connect a resistor to the Pin 25, and then, connect to the Pin 26.	
26	MOD input	DC=2V Z=OPEN Emitter FM modulation circuit input pin. Connect a resistor. (Resistor between pins 25 and 26): For deviation control (Resistor between pin 26 and Vcc): For fo control	
27	W-clip adjustment	OPEN Base White clip level control pin. LoLine noise canceller Off Connect the VR.	9 V v v v v v v v v v v v v v v v v v v
28	PB FM input	DC=3.3V Z=10kΩ PB FM signal input pin.	Vcc 23
29	Envelop detection	DC=2.3V (no RF input) Z=30kΩ FM signal envelop detection pin.	Vcc 29
30	FM output	DC=3.8V Z=200Ω+OPEN Emitter AC= REC FM 1V FM modulation signal output pin. DOC pulse output pin at PB. Connect a resistor.	Vcc − 30

Note: The above characteristics are reference design values, and not guarantee values.

■ Characteristic Curves





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